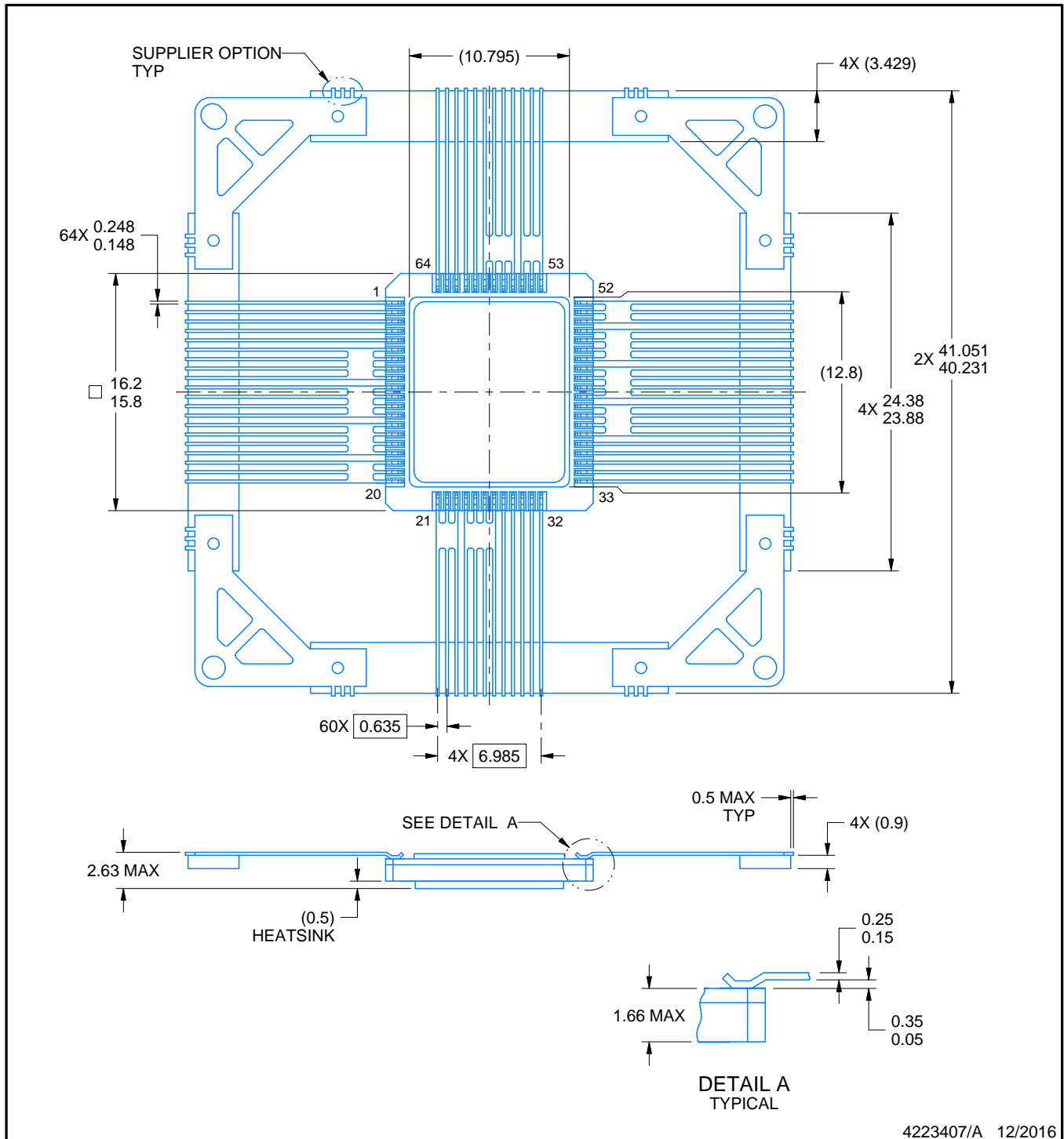


# PACKAGE OUTLINE

HFG0064A

CFP - 2.63 mm max height

CERAMIC FLATPACK



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NOTES:

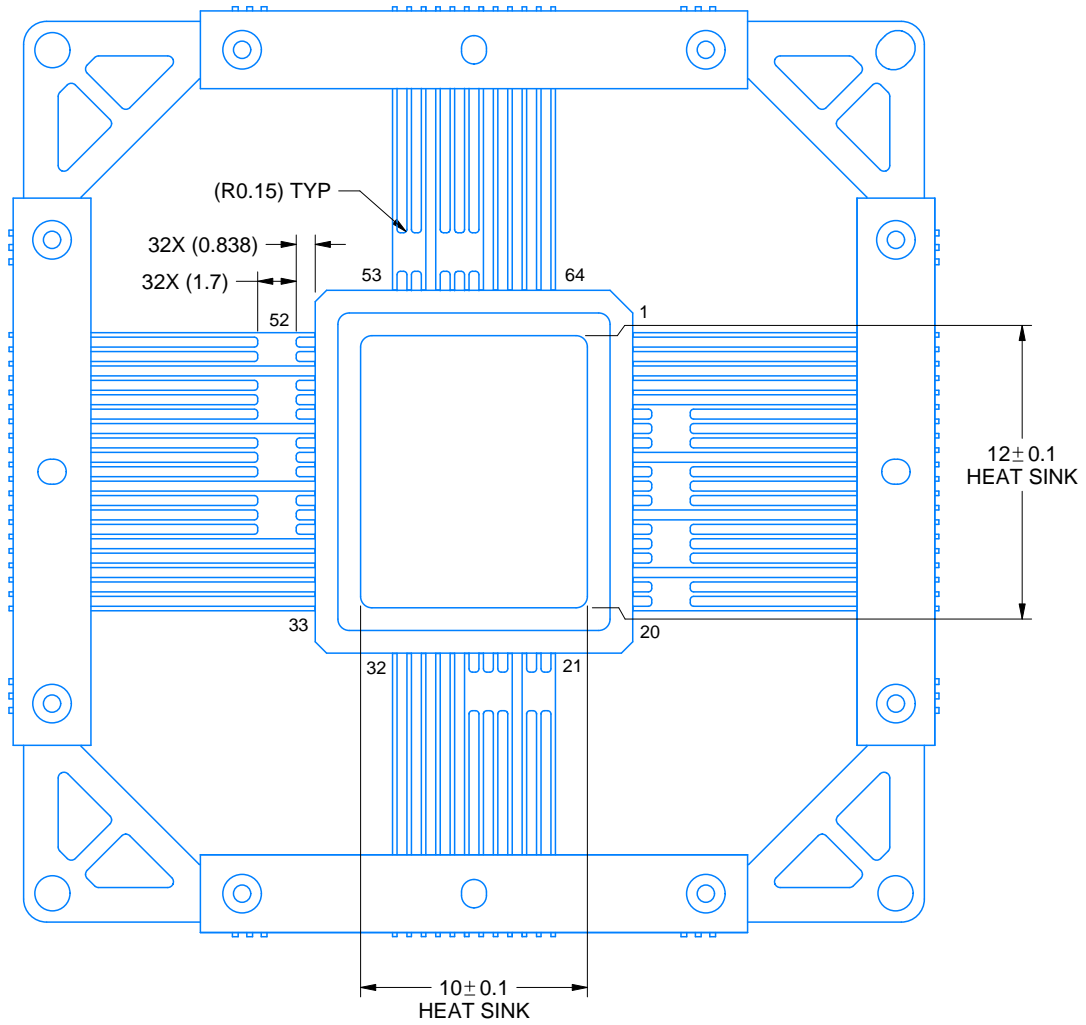
1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. This package is hermetically sealed with a metal lid.
4. The lid and the heat sink are connected to ground leads.
5. The leads are gold plated and can be solder dipped.

# PACKAGE OUTLINE

HFG0064A

CFP - 2.63 mm max height

CERAMIC FLATPACK



BACK VIEW  
SCALE:3X

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